



SEMITOP® 2

Antiparallel Thyristor Module

SK 45 WT

Preliminary Data

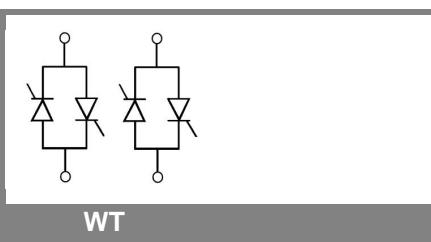
Features

- Compact Design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DBC)
- Glass passivated thyristor chips
- Up to 1600V reverse voltage
- UL recognized, file no. E 63 532

Typical Applications

- Soft starters
- Light control (studios, theaters...)
- Temperature control

V_{RSM}	V_{RRM}, V_{DRM}	$I_{RMS} = 47 \text{ A A (full conduction)}$ $(T_s = 85^\circ\text{C})$	
V	V	$SK 45 \text{ WT } 08$	
900	800	$SK 45 \text{ WT } 12$	
1300	1200	$SK 45 \text{ WT } 16$	
1700	1600		
Symbol	Conditions	Values	Units
I_{RMS}	$W1C ; \sin. 180^\circ ; T_s = 100^\circ\text{C}$ $W1C ; \sin. 180^\circ ; T_s = 85^\circ\text{C}$	33 47	A A
I_{TSM}	$T_{vj} = 25^\circ\text{C} ; 10 \text{ ms}$ $T_{vj} = 125^\circ\text{C} ; 10 \text{ ms}$	450 380	A A
i^2t	$T_{vj} = 25^\circ\text{C} ; 8,3\dots10 \text{ ms}$ $T_{vj} = 125^\circ\text{C} ; 8,3\dots10 \text{ ms}$	1000 720	A^2s A^2s
V_T	$T_{vj} = 25^\circ\text{C}, I_T = 75 \text{ A}$	max. 1,9	V
$V_{T(TO)}$	$T_{vj} = 125^\circ\text{C}$	max. 1	V
r_T	$T_{vj} = 125^\circ\text{C}$	max. 10	$\text{m}\Omega$
$I_{DD}; I_{RD}$	$T_{vj} = 25^\circ\text{C}, V_{RD}=V_{RRM}$ $T_{vj} = 125^\circ\text{C}, V_{RD}=V_{RRM}$	max. 0,5 max. 10	mA mA
t_{gd}	$T_{vj} = 25^\circ\text{C}, I_G = 1 \text{ A}; di_G/dt = 1 \text{ A}/\mu\text{s}$	1	μs
t_{gr}	$V_D = 0,67 * V_{DRM}$	2	μs
$(dv/dt)_{cr}$	$T_{vj} = 125^\circ\text{C}$	1000	$\text{V}/\mu\text{s}$
$(di/dt)_{cr}$	$T_{vj} = 125^\circ\text{C}; f= 50\dots60 \text{ Hz}$	50	$\text{A}/\mu\text{s}$
t_q	$T_{vj} = 125^\circ\text{C}; \text{typ.}$	120	μs
I_H	$T_{vj} = 25^\circ\text{C}; \text{typ. / max.}$	80 / 150	mA
I_L	$T_{vj} = 25^\circ\text{C}; R_G = 33 \Omega ; \text{typ. / max.}$	150 / 300	mA
V_{GT}	$T_{vj} = 25^\circ\text{C}; \text{d.c.}$	min. 3	V
I_{GT}	$T_{vj} = 25^\circ\text{C}; \text{d.c.}$	min. 100	mA
V_{GD}	$T_{vj} = 125^\circ\text{C}; \text{d.c.}$	max. 0,25	V
I_{GD}	$T_{vj} = 125^\circ\text{C}; \text{d.c.}$	max. 3	mA
$R_{th(j-s)}$	cont. per thyristor $\sin 180^\circ$ per thyristor	1,2 1,24	K/W
$R_{th(j-s)}$	cont. per W1C $\sin 180^\circ$ per W1C	0,6 0,62	K/W
T_{vj}		-40 ... +125	°C
T_{stg}		-40 ... +125	°C
T_{solder}	terminals, 10s	260	°C
V_{isol}	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3000 / 2500	V~
M_s	Mounting torque to heatsink	1,5	Nm
M_t			Nm
a		13	m/s^2
m			g
Case	SEMITOP® 2	T 37	



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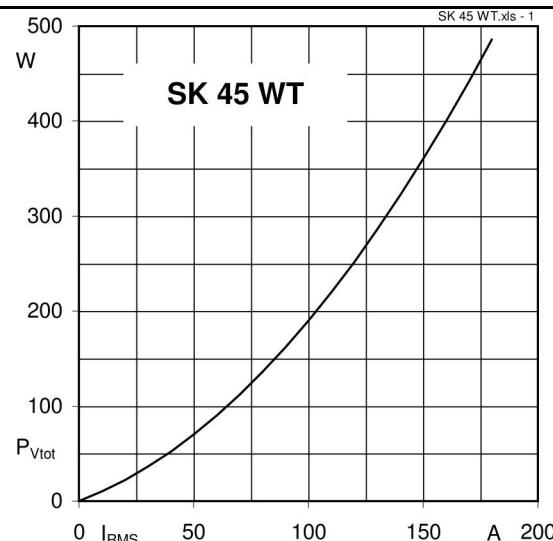


Fig. 1 Power dissipation per phase vs. r.m.s. current

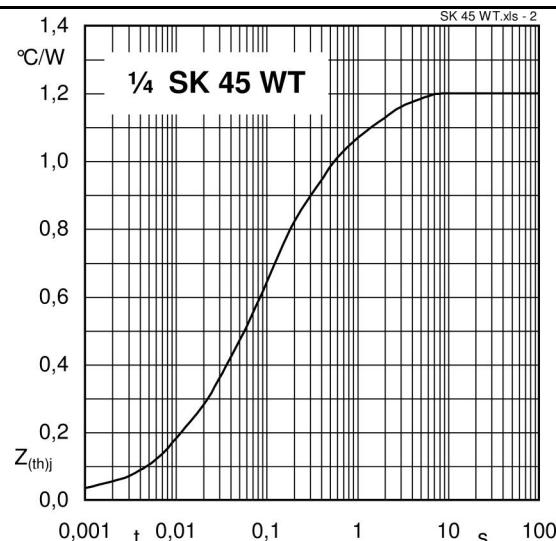


Fig. 2 Transient thermal impedance vs. time

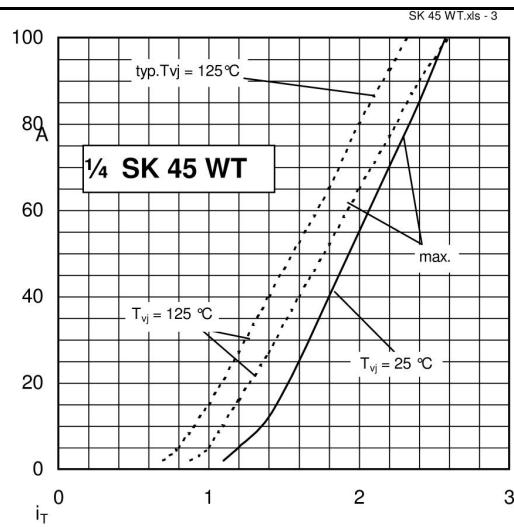


Fig. 3 On-state characteristics

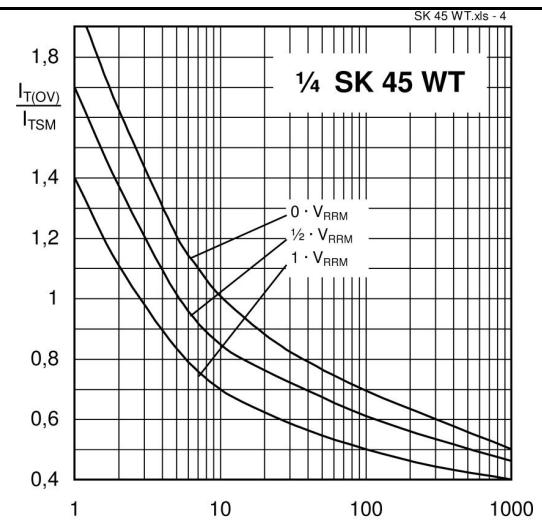


Fig. 4 Surge overload current vs. time

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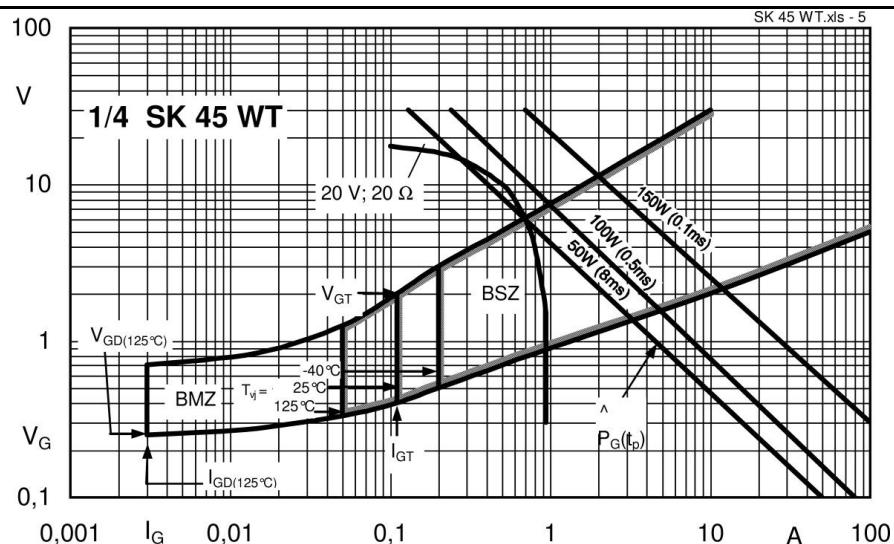
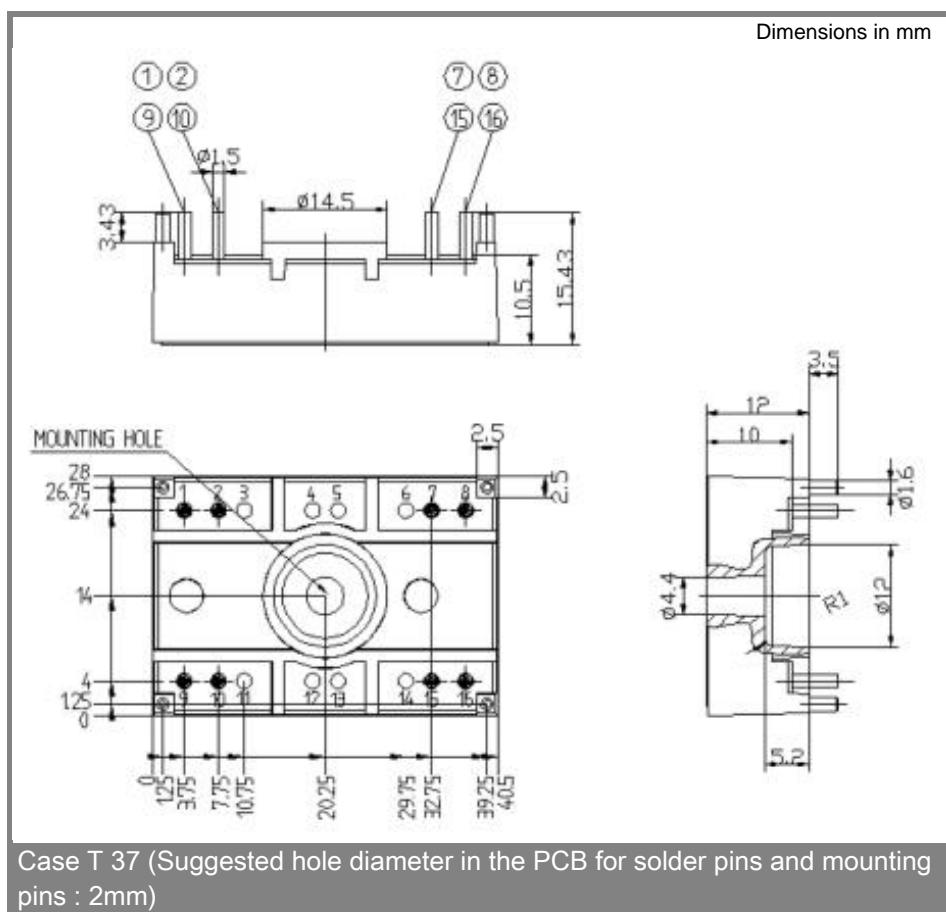


Fig. 5 Gate trigger characteristics



Case T 37 (Suggested hole diameter in the PCB for solder pins and mounting pins : 2mm)

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